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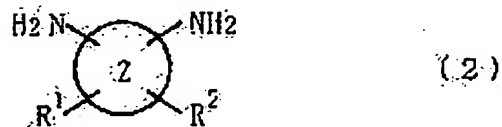
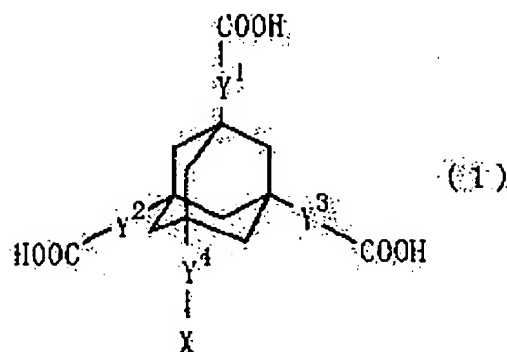
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(54) INSULATING FILM-FORMING MATERIAL AND INSULATING FILM

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a material forming a polybenzazole insulating film which has high heat resistance and a low dielectric constant and is useful for a semiconductor part and the like.

SOLUTION: The insulating film-forming material comprises a polymerizable composition obtained by dissolving an adamantane polycarboxylic acid represented by formula (1) (wherein X is a hydrogen atom, a carboxyl group or a hydrocarbon group; and Y1, Y2, Y3 and Y4 are the same or different and are each a single bond or a divalent aromatic cyclic group) and an aromatic polyamine represented by formula (2) (wherein the ring Z is a monocyclic or polycyclic aromatic ring; and R1 and R2 are each a substituent group bonded to the ring Z and are, same or different, an amino group, a mono-substituted amino group, a hydroxyl group or a mercapto group) in a solvent other than a ketone and an aldehyde.



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